



Material Content Data Sheet



Sales Product Name		TLF50241EL		Issued		28. August 2013		
MA#		MA001056010						
Package		PG-SSOP-14-3		Weight*		82.97 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.797	2.17	2.17	21665	21665
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.689	0.83		8305	
wire	non noble metal	copper	7440-50-8	27.978	33.72	34.60	337221	346045
	noble metal	gold	7440-57-5	0.152	0.18	0.18	1836	1836
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1203
encapsulation	plastics	epoxy resin	-	4.591	5.53		55342	
	inorganic material	silicondioxide	60676-86-0	45.216	54.50	60.15	545000	601545
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11765	11765
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9252	9252
glue	plastics	epoxy resin	-	0.164	0.20		1973	
	noble metal	silver	7440-22-4	0.491	0.59	0.79	5919	7892
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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